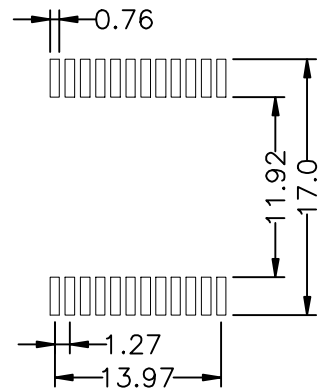
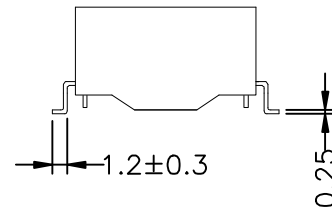
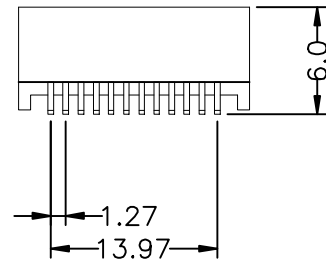
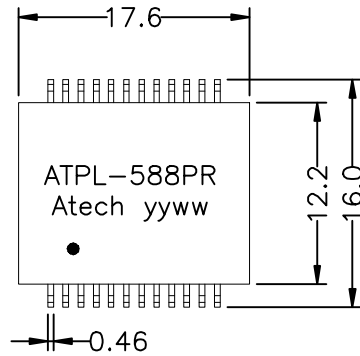
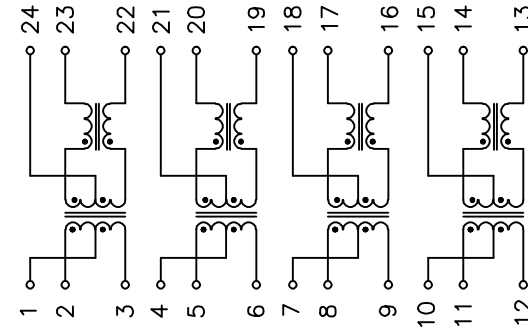




SUGGESTED PCB LAYOUT

UNLESS OTHERWISE SPECIFIED ALL TOLERANCES ARE $\pm 0.25\text{mm}$



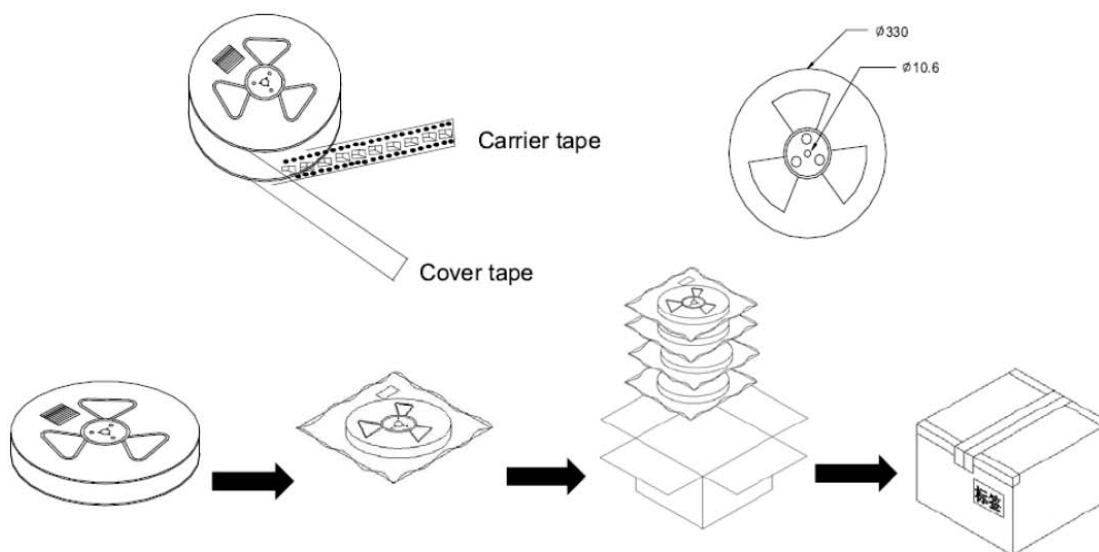
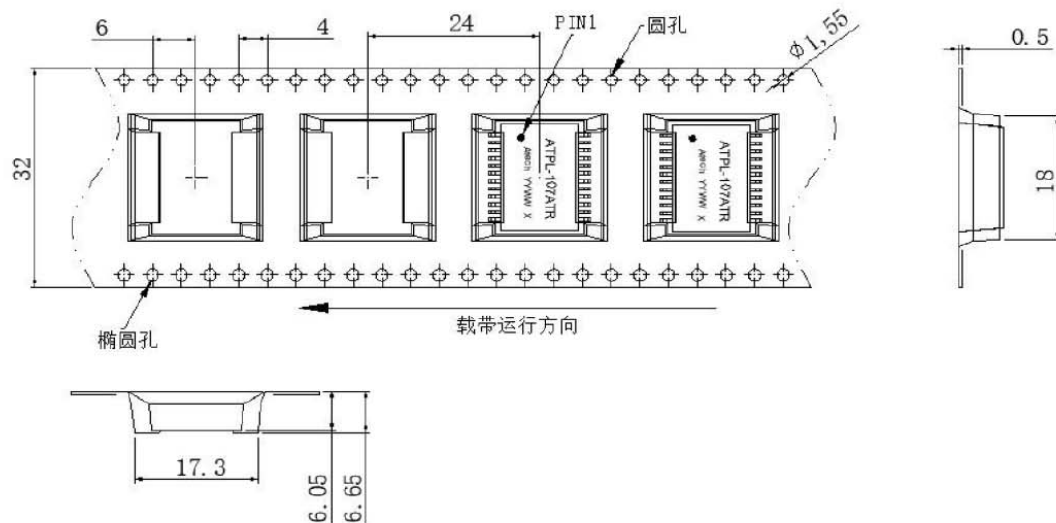
* RoHS COMPLIANT

ELECTRICAL CHARACTERISTICS @25°C :

1. INSULATION HI-POT : 1500 Vrms/1mA ,60Sec.
2. TURN RATIO ($\pm 5\%$) : 1CT : 1CT
3. OCL : : (@100kHz, 0.1Vrms, 8mA DC BIAS) : 120uH MIN.
4. CROSS TALK (dB MIN.) : 1-100MHz 100-500MHz
-35 -30
5. INSERTION LOSS : 1-250MHz : -1.5dB MAX.
250-500MHz : -3.0dB MAX.
6. RETURN LOSS : 1-40MHz : -16dB MIN.
40-500MHz : -16+10log(f/40)dB MIN.
7. DIFFERENTIAL TO COMMON MODE REJECTION (dB MIN.) :
1-250MHz 250-500MHz
-30 -20
8. Comply with IEEE802.3at
9. SUITABLE FOR PoE APPLICATIONS WITH 600mA CURRENT
10. OPERATING TEMPERATURE RANGE : 0°C to +70°C
11. STORAGE TEMPERATURE : -25°C to +105°C

						AOEM		TITLE 10G BASE-T TRANSFORMER	
								DWG. NO. ATPL-588PR	
	RELEASE	05/11/2023	SHIRLEY	BETTY	BETTY	UNITS: M/M	SAFETY		SHEET 1 of 1
NO:	DESCRIPTION	DATE	BY	CHK	APPD	DATE	P/N:	DRAW	
REVISIONS						05/11/23			SHIRLEY

3. Package:



Product	PCS/Reel	PCS/Box	Product No.	Weight(g/pcs)
SMD 24 PIN Series	400	400x6=2400		1.45

Remarks:

- 1) Packing Level & Storage Condition based on MSL1
- 2) ESD package
- 3) Parts packaging meet EIA-481 standard (pull 0.26N~1.3N)

Pb-free Soldering Heat Withstanding Survey

SUGGEST PROFILE



reflow profile

Form-1 (Reference JEDEC J-STD-020D Table 5-2))

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max	3°C/second max
Preheat Temperature Min (Tsmmin)	100°C	150°C
Temperature Min (Tsmax)	150°C	200°C
Time (Tsmmin to Tsmax) (ts)	60-120seconds	60-180seconds
Time maintained above Temperature (TL)	183°C	217°C
Time (tL)	60-150seconds	60-150seconds
Peak Temperature (Tp)	225°C	260°C
Time within 5°C of actual Peak Temperature (Tp) ²	20 seconds	30 seconds
Ramp-down Rate	6°/second max	6°/second max
Time 25°C to Peak Temperature	6minutes max	8minutes max